

Features

- 5050 top view SMD LED
- High Brightness
- AllnGaP / InGaN Technology
- Small package
- High reliability
- Clear Lens

Applications

- Consumer Electronics
- Light pipe application
- Automobile After Market
- Industrial Equipment

Description

The IN-P55TATRGB is a popular low profile RGB 5050 package with versatile design capabilities. It is a PLCC type LED which can be used in various applications.

Recommended Solder Pattern

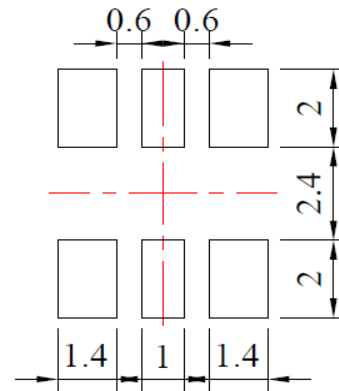


Figure 1. IN-P55TATRGB Solder Pattern

Package Dimensions in mm

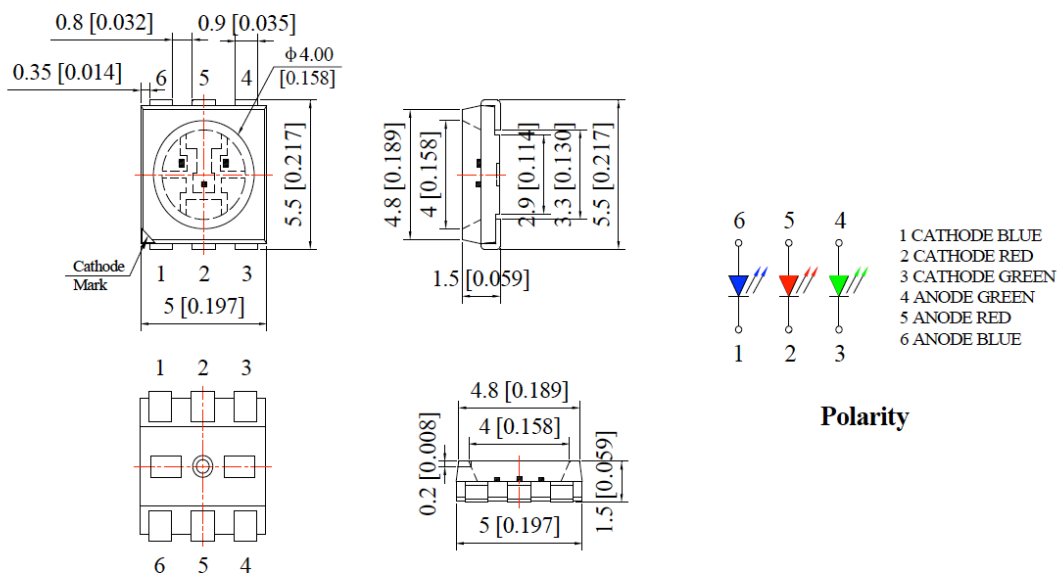


Figure 2. IN-P55TATRGB Package Dimensions

Absolute Maximum Rating at 25°C (Note 1)

| Product | Emission Color | P _d (mW) | I _F (mA) | I _{FP} * (mA) | V _R (V) | T _{OP} (°C) | T _{ST} (°C) |
|--------------|----------------|---------------------|---------------------|------------------------|--------------------|----------------------|----------------------|
| IN-P55TATRGB | Red | 60 | 25 | 100 | 5 | -40°C~+80°C | -40°C~+85°C |
| IN-P55TATRGB | Green | 95 | 25 | 100 | 5 | -40°C~+80°C | -40°C~+85°C |
| IN-P55TATRGB | Blue | 95 | 25 | 100 | 5 | -40°C~+80°C | -40°C~+85°C |

Notes

1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

Electrical Characteristics T_A = 25°C (Note 1)

| Product | Emission Color | I _F (mA) | V _F (V) | | λ(nm) | | | Viewing Angle | I _v (mcd) |
|--------------|----------------|---------------------|--------------------|-----|----------------|----------------|----|---------------|----------------------|
| | | | min | max | λ _D | λ _P | Δλ | 2θ 1/2 | typ. |
| IN-P55TATRGB | Red | 20 | 1.6 | 2.4 | 624 | 632 | 20 | 120 | 900 |
| IN-P55TATRGB | Green | 20 | 2.8 | 3.4 | 520 | 525 | 35 | 120 | 1800 |
| IN-P55TATRGB | Blue | 20 | 2.8 | 3.4 | 468 | 470 | 25 | 120 | 600 |

Notes

1. Performance guaranteed only under conditions listed in above tables.

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

Luminous Intensity (Iv) Bin:

| Color | Bin Code | Spec. Range |
|-------|----------|---------------|
| Red | B1 | 600-700 mcd |
| | B2 | 700-800 mcd |
| | B3 | 800-900 mcd |
| | B4 | 900-1000 mcd |
| | B5 | 1000-1100 mcd |
| | B6 | 1100-1200 mcd |
| Green | E1 | 1500-1600 mcd |
| | E2 | 1600-1700 mcd |
| | E3 | 1700-1800 mcd |
| | E4 | 1800-1900 mcd |
| | E5 | 1900-2000 mcd |
| | E6 | 2000-2100 mcd |
| Blue | H1 | 300-400 mcd |
| | H2 | 400-500 mcd |
| | H3 | 500-600 mcd |
| | H4 | 600-700 mcd |
| | H5 | 700-800 mcd |
| | H6 | 800-900 mcd |

@20mA / Ta=25° C, Tolerance: ± 10%

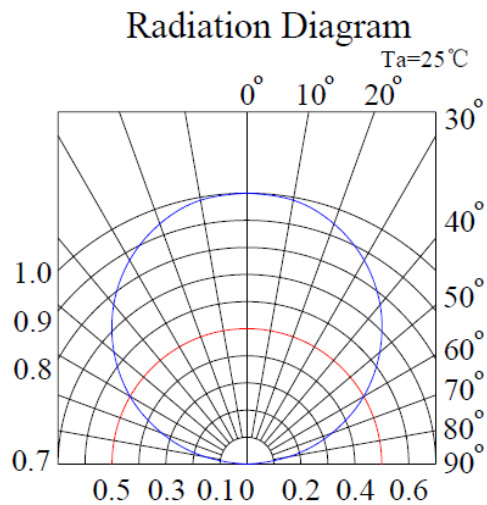
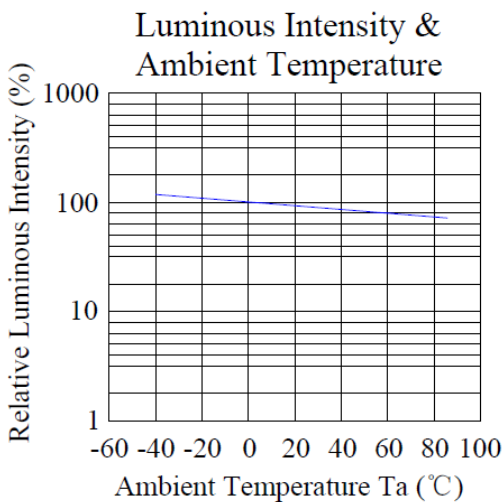
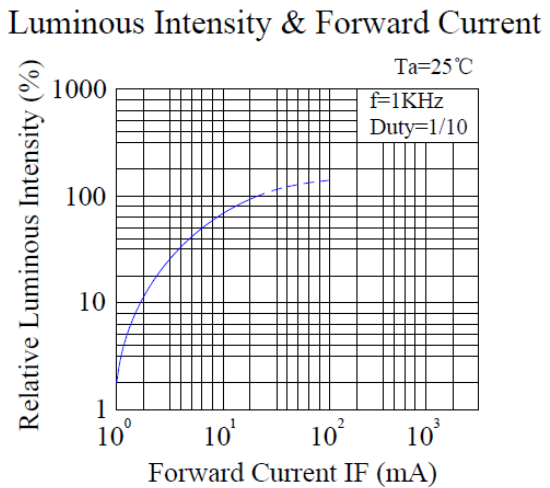
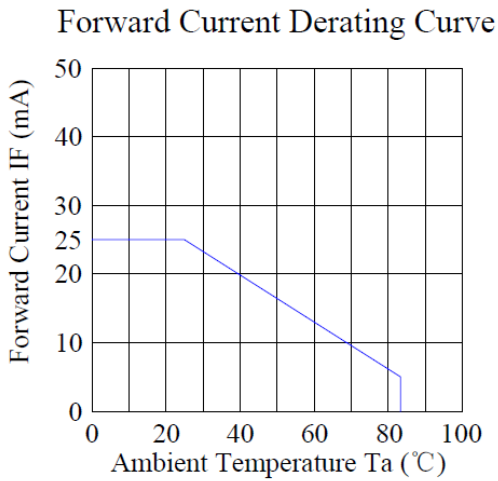
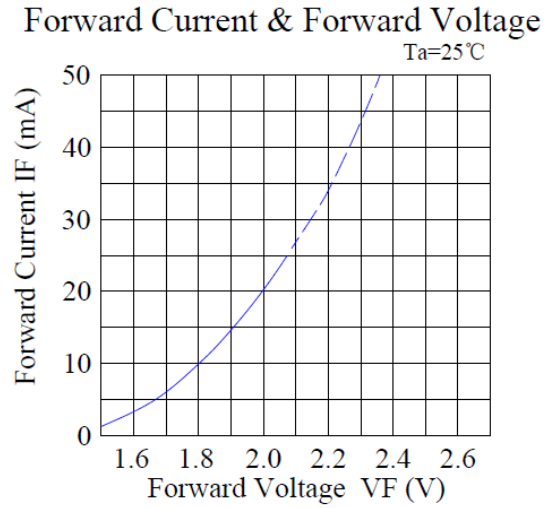
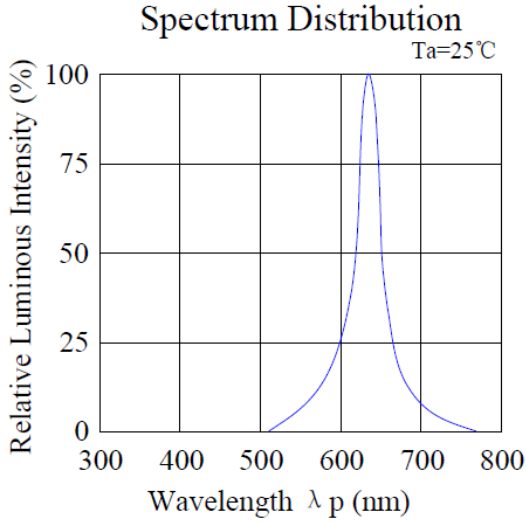
Dominant Wavelength (λD) Bin:

| Color | Bin Code | Spec. Range |
|-------|----------|-------------|
| Red | A1 | 620-625 nm |
| | A2 | 625-630 nm |
| | A3 | 630-635 nm |
| Green | D1 | 520-525 nm |
| | D2 | 525-530 nm |
| | D3 | 530-535 nm |
| Blue | G1 | 460-465 nm |
| | G2 | 465-470 nm |
| | G3 | 470-475 nm |

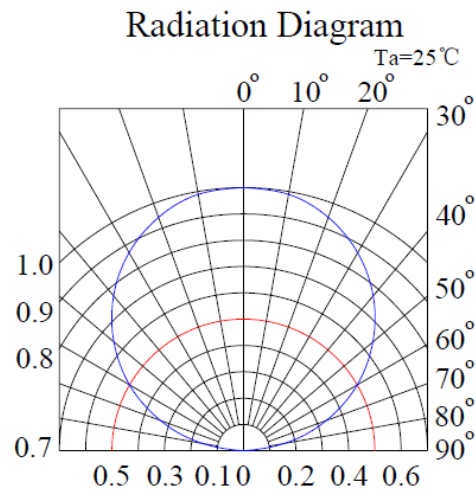
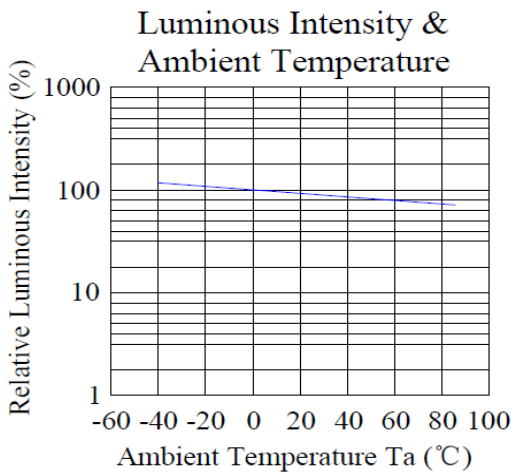
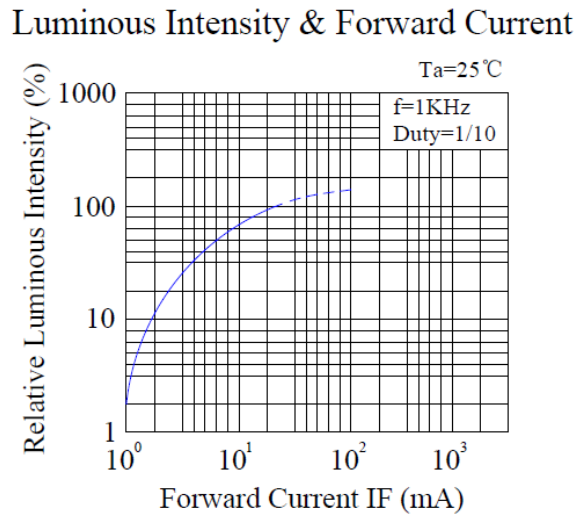
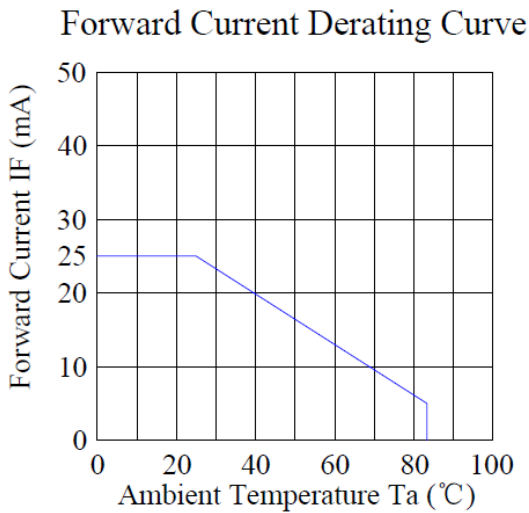
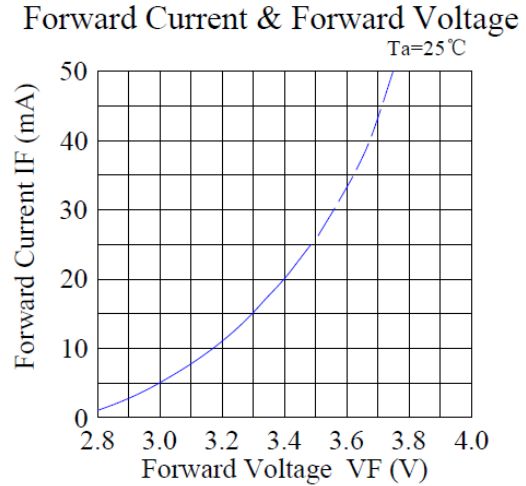
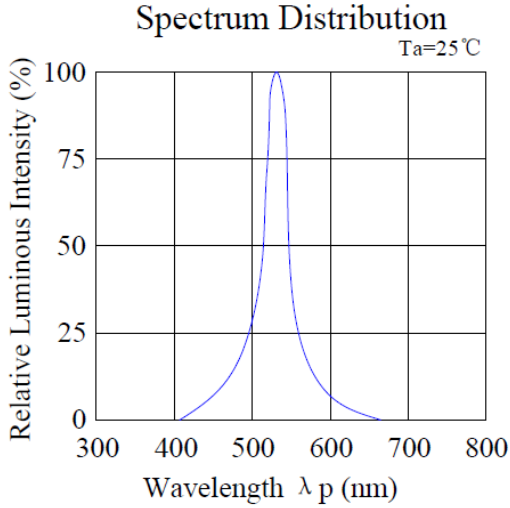
Forward Voltage (Vf) Bin:

| Color | Bin Code | Spec. Range |
|-------|----------|-------------|
| Red | C0 | 1.80-2.00 V |
| | C1 | 2.00-2.20 V |
| | C2 | 2.20-2.40 V |
| Green | F1 | 2.80-3.00 V |
| | F2 | 3.00-3.20 V |
| | F3 | 3.20-3.40 V |
| Blue | V1 | 2.80-3.00 V |
| | V2 | 3.00-3.20 V |
| | V3 | 3.20-3.40 V |

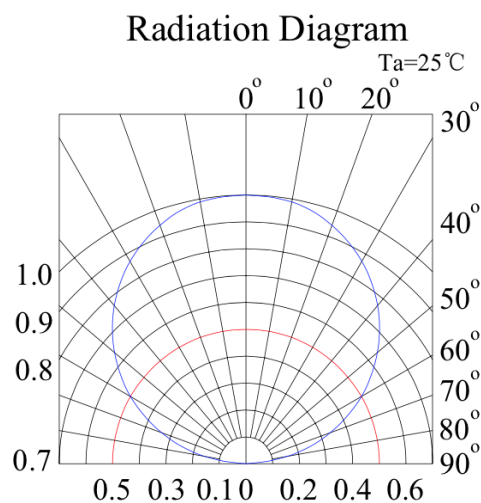
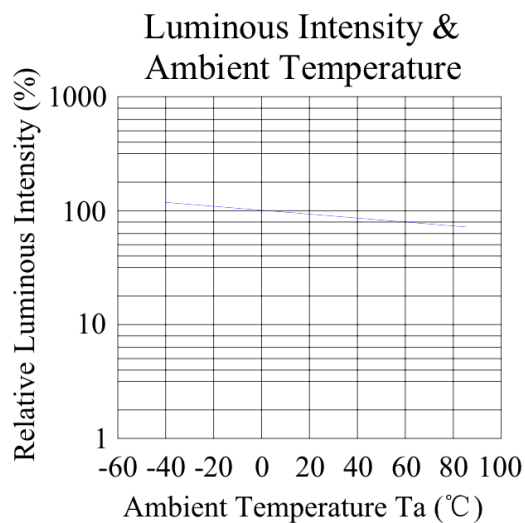
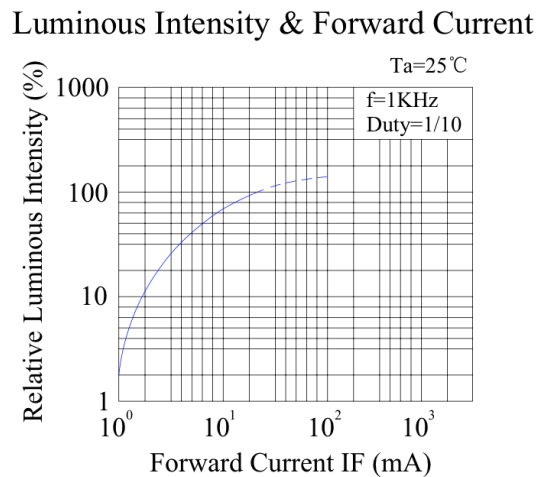
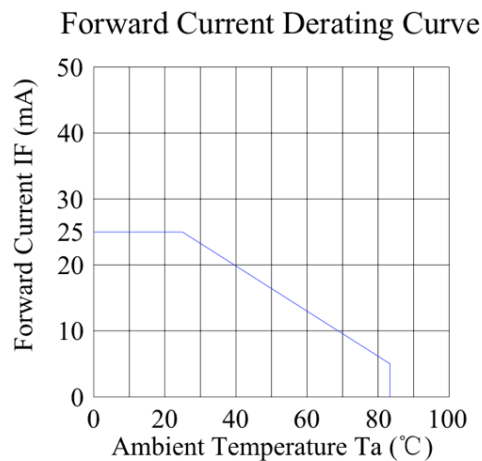
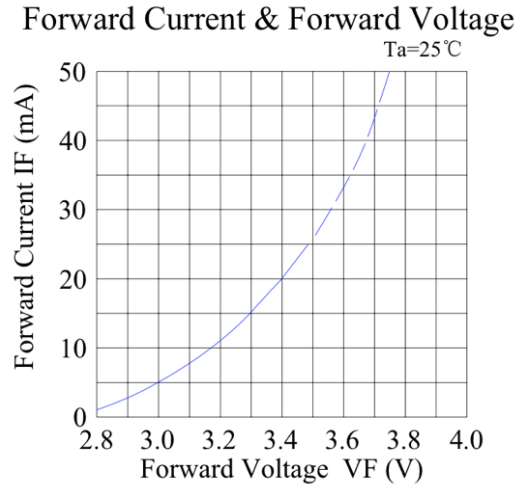
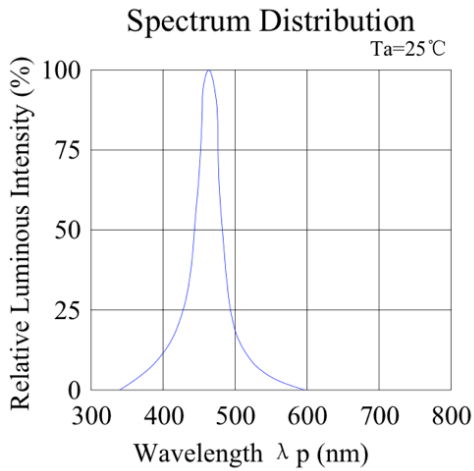
Typical Characteristic Curves-Red



Typical Characteristic Curves-Green



Typical Characteristic Curves-Blue

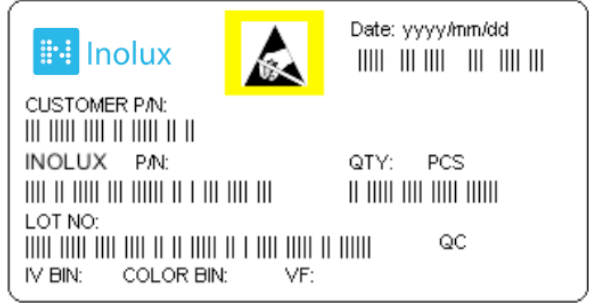


Ordering Information

| Product | Emission Color | Technology | Test Current I_F (mA) | Luminous Intensity I_V (mcd) (Typ.) | Forward Voltage V_F (V) (Typ.) | Orderable Part Number |
|--------------|----------------|------------|----------------------------|---|--|-----------------------|
| IN-P55TATRGB | Red | AllnGaP | 20 | 900 | 2.0 | IN-P55TATRGB |
| | Green | InGaN | 20 | 1800 | 3.2 | |
| | Blue | InGaN | 20 | 600 | 3.2 | |

- Bin Range specified on page 3.

Label Specifications

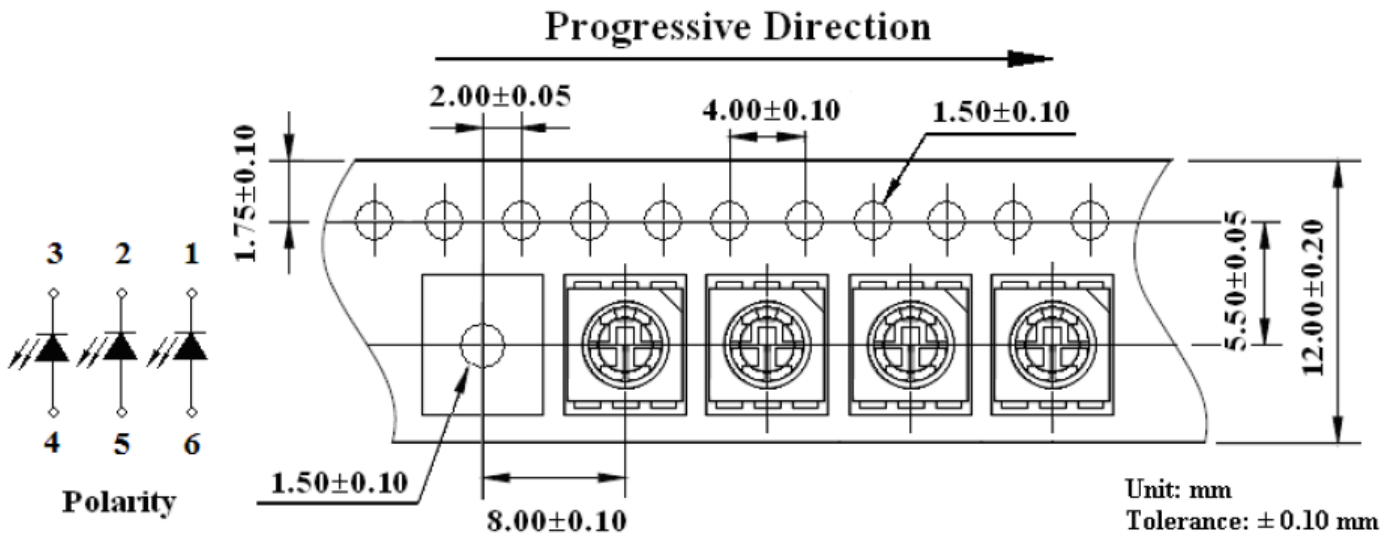
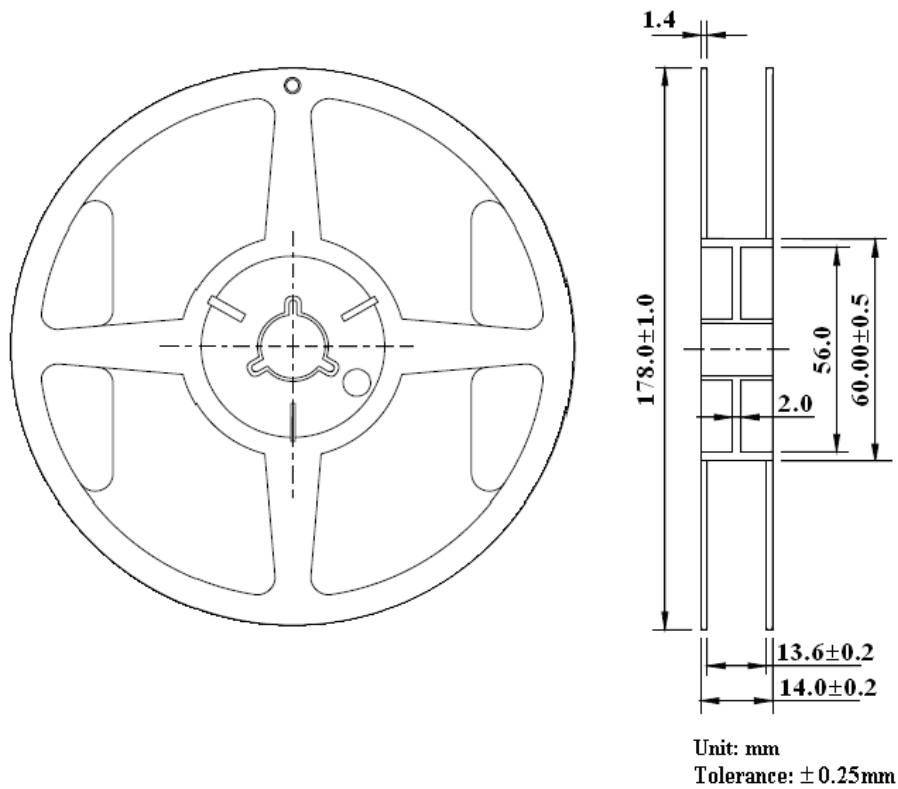


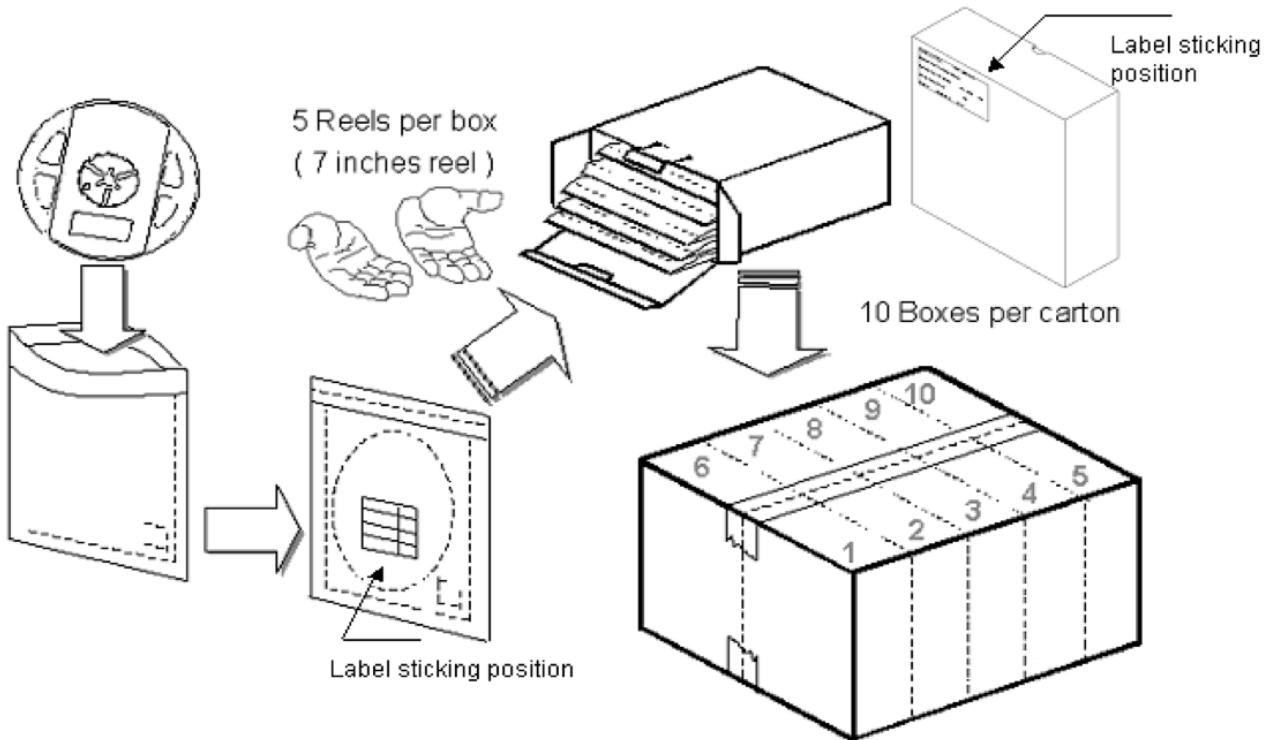
Inolux P/N:

| I | N | - | P | 5 | 5 | TA | T | | | R | G | B | - | X | X | X | X |
|--------|-----|---|---------------|---------------------------|---|-----------|---------------|-------------------------|-----------------|-------------------------------|---|---|---|----------------------|---|---|---|
| | | | Material | Package | | Variation | Orientation | Current | Lens | Color | | | | Customized Stamp-off | | | |
| Inolux | SMD | | P = PLCC Type | 55TA = 5.0 x 5.5 x 1.5 mm | | | T = Top Mount | (Blank) = 20mA per Chip | (Blank) = Clear | R=632nm G=520nm B=470nm | | | | | | | |

Lot No.:

| | | | | | | | |
|------------------|--------------------------|---|---|---|-------|------|--------|
| Z | 2 | 0 | 1 | 7 | 01 | 24 | 001 |
| Internal Tracker | Year (2017, 2018,) | | | | Month | Date | Serial |

Packaging Information: 1000pcs Per Reel
Tape Dimension

Reel Dimension


Packing Dimension


5 boxes per carton are available depending on shipment quantity.

| | Specification | Material | Quantity |
|--------------|----------------------|-----------------------------------|------------------|
| Carrier tape | Per EIA 481-1A specs | Conductive black tape | 1000pcs per reel |
| Reel | Per EIA 481-1A specs | Conductive black | |
| Label | IN standard | Paper | |
| Packing bag | 220x240mm | Aluminum laminated bag/ no-zipper | One reel per bag |
| Carton | IN standard | Paper | Non-specified |

Others:

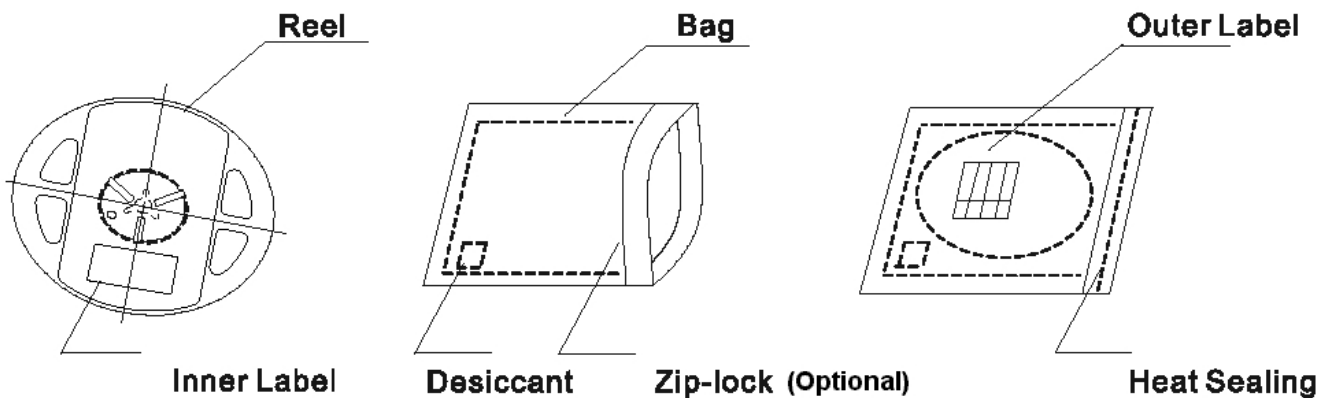
Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of I_V , λ_D and V_f . Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

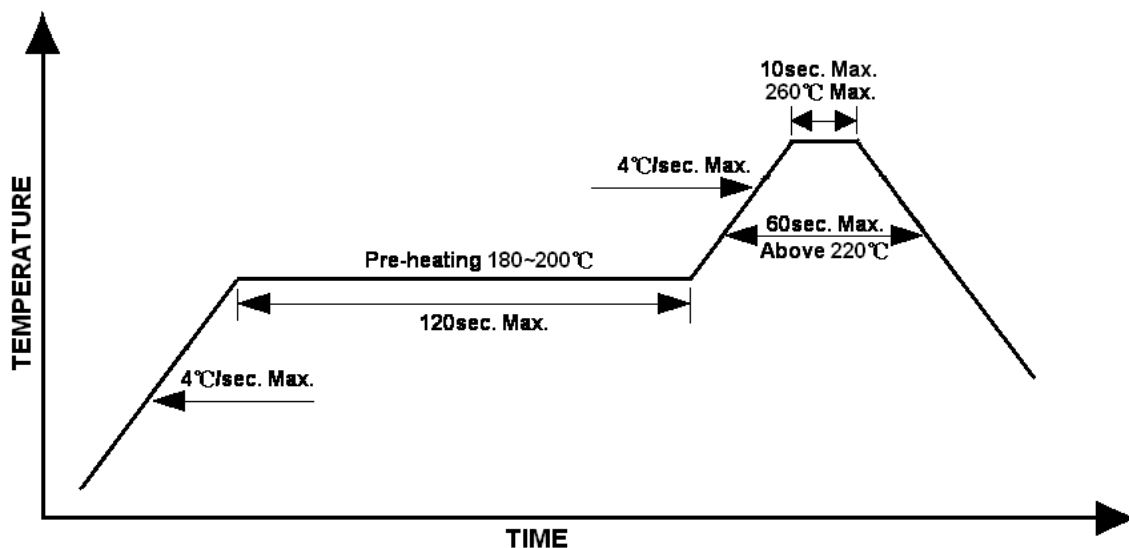
The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead-free Solder Profile



Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Reliability

| Item | Frequency/ lots/ samples/ failures | Standards Reference | Conditions |
|--------------------------------------|---|--------------------------------|--|
| Precondition | For all reliability monitoring tests according to JEDEC Level 2 | J-STD-020 | 1.) Baking at 85°C for 24hrs 2.) Moisture storage at 85°C/ 60% R.H. for 168hrs |
| Solderability | 1Q/ 1/ 22/ 0 | JESD22-B102-B And CNS-5068 | Accelerated aging 155°C/ 24hrs Tinning speed: 2.5+0.5cm/s Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s |
| Resistance to soldering heat | | CNS-5067 | Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s |
| Operating life test | 1Q/ 1/ 40/ 0 | CNS-11829 | 1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs |
| High humidity, high temperature bias | 1Q/ 1/ 45/ 0 | JESD-A101-B | Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs |
| High temperature bias | 1Q/ 1/ 20 | IN specs. | Tamb: 55°C IF=20mA Duration: 1000hrs |
| Pulse life test | 1Q/ 1/ 40/ 0 | | Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125 μs, T=1sec) Duration 500hrs) |
| Temperature cycle | 1Q/ 1/ 76/ 0 | JESD-A104-A IEC 68-2-14, Nb | A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min.. 300 cycles 2 chamber/ Air-to-air type |
| High humidity storage test | 1Q/ 1/ 40/ 0 | CNS-6117 | 60+3°C 90+5/-10% R.H. for 500hrs |
| High temperature storage test | 1Q/ 1/ 40/ 0 | CNS-554 | 100+10°C for 500hrs |
| Low temperature storage test | 1Q/ 1/ 40/ 0 | CNS-6118 | -40+5°C for 500hrs |

Revision History

| Changes since last revision | Page | Version No. | Revision Date |
|-----------------------------|------|-------------|---------------|
| Initial Release | | 1.0 | 04-26-2017 |
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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.